

Heat Sink Compound

1. General description

Compound to increase the thermal conductivity and the efficient heat dissipation at electronic components.

2. Features

- High thermal conductivity.
- Excellent moisture buffer.
- Low metallic impurity content.

3. Applications

- Printed circuit boards.
- Electronic components.
- Control assemblies.

4. Directions

- Apply to a clean, dry surface.
- Do not mix with other products.
- Do not use on energized equipment.
- **A safety data sheet (MSDS) according to EC Regulation N° 1907/2006 Art.31 and amendments is available for all CRC products.**

5. Typical product data (without propellant)

Appearance	Paste.
Color	White.
Odor	Characteristic odor.
Density	2.3 g/cm ³ (@ 20°C).
Operating temperature active product	-50 --> 300 °C

Remarks

All statements in this publication are based on service experience and/or laboratory testing. Because of the wide variety of equipment, conditions of use and the unpredictable human factors involved, we recommend that our products are tested on-the-job prior to use. All information is given in good faith but without warranty neither expressed nor implied. This Technical Data Sheet may already have been revised as a result of a change in legislation, availability of components or newly acquired experiences. The latest and only valid version of this Technical Data Sheet will be sent to you upon simple request or can be found on our website: www.crcind.com We recommend that you register on our website for this product, thus enabling you to automatically receive any future updates.

Version

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Technical Data Sheet

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